

9. Judul Artikel : Modelling Temperature Effect on (Transverse Electric) TE Mode Shape of Optical Silica Waveguide
Penulis : Indrawan Arifianto, Muhammad Rangga Hadisiswoyo, **Ary Syahriar**.
Nama Jurnal : Universal Journal of Electrical and Electronic Engineering
Volume Jurnal : 6
Nomor Jurnal : 3
Tahun Terbit Jurnal : 2019
Halaman : 147 – 150
ISSN : 2332 – 3280
Penerbit : Horizon Research Publishing

Komentar dari Reviewer :

Universal Journal of Electrical and Electronic Engineering Discontinued in Scopus as of 2019
Informasi tim editor kurang jelas: <https://www.hrpub.org/contact.php> Mohon dilengkapi dengan dokumen proses korespondensi.

Revisi (Klarifikasi/Penjelasan) :

Berikut korespondensi untuk karya ilmiah tersebut.

ok thanks you, I will send as soon as possible

Pada tanggal Sel, 7 Mei 2019 21.30 The 4th International Conference on Computing Mathematics and Statistics 2019 <icms2019@uitm.edu.my> menulis:

Dear Author,

Thank you for your email.

Please follow the template given and email to us before 14th May 2019.

-----indrawan arifianto <indrawanarifianto1997@gmail.com> wrote: -----

=====

To: The 4th International Conference on Computing Mathematics and Statistics 2019
<icms2019@uitm.edu.my>

From: indrawan arifianto <indrawanarifianto1997@gmail.com>

Date: 05/07/2019 10:20PM

Subject: Re: INVITATION TO PUBLISH IN SPECIAL ISSUE

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yes im interest

Pada tanggal Sel, 7 Mei 2019 21.05 The 4th International Conference on Computing Mathematics and Statistics 2019 <icms2019@uitm.edu.my> menulis:

> Dear Author,

>

> INVITATION TO PUBLISH IN SPECIAL ISSUE

>

> Greetings from iCMS2019 organizing committee. We are pleased to inform you
> that your paper

>

>

> *iCMS2019-150*

>

> *Modelling Temperature Effect on (Transverse Electric) TE mode Shape of
> optical Silica Waveguide*

>

>

> was selected and recommended to be submitted for publication in one of
> following journals:

>

> i) Universal Journal of Mechanical Engineering (UJME) (ISSN:
> 2332-3361) which is indexed by SCOPUS

> <https://www.scopus.com/sourceid/21100855996?origin=resultslist>

>

> ii) Mathematics and Statistics (ISSN: 2332-2071 / 2332-2144). This
> journal has passed the final evaluation of SCOPUS and the coverage
> agreement has been signed. SCOPUS Progress Tracking

>

>

> <http://suggestor.step.scopus.com/progressTracker/?trackingID=52D964231257E57F>

>

> iii) Civil Engineering and Architecture (ISSN: 2332-1091 / 2332-1121).

> This journal has also passed the final evaluation of SCOPUS and the

> coverage agreement has been signed. SCOPUS Progress Tracking:

> <http://suggestor.step.scopus.com/progressTracker/index.cfm?trackingID=5D14FD130C4CBC0C>

>

>
> The paper, however, will be subjected to the journal's final review
> process and acceptance of publication is determined by the Chief Editor of
> the journal.
>
> To proceed with the publication, iCMS2019 is offering a discount of 50%
> off the normal publication fee (USD290). This means that another 50%
> (USD145) is to be borne by the author and needs to be paid when the paper
> is accepted.
>
> If the above term is agreeable with you, you are required to revise your
> manuscript using the attached guidelines. Please send us the revise version
> via e-mail (icms2019@uitm.edu.my) before 14th May 2019. Name your file as
> : iCMS2019_(Paper ID).
>
>
> Kindly convey your decision (accept or not accept*) by replying to this
> e-mail.
>
> *Please let us know why?
>
> 1. Prefer to publish in conference proceeding or Journal of Creative
> Practices in Language Learning and Teaching (CPLT)
> <<https://cplt.uitm.edu.my/v1/>>
>
> 2. I am still considering "Austrian Journal of Statistics
> <<http://www.ajs.or.at/index.php/ajs>>" or "Romanian Statistical Review
> <<http://www.revistadestatistica.ro/index.php/>>" to review my paper.
>
> 3. Other reason : _____
>
>
>
> Thank you in advance for your cooperation.
>
> Best Regards,
> iCMS2019 Publication Committee
>
>

Dear Dr. Indrawan Arifianto,

We are pleased to inform you that your paper has been published, Please refer to the following information for detail:

PAPER_TITLE: Modelling Temperature Effect on (Transverse Electric) TE Mode Shape of Optical Silica Waveguide

ARTICLE_INFO: http://www.hrpub.org/journals/article_info.php?aid=8202

Download Info: <http://www.hrpub.org/download/20190730/UJEEEE8-14990622.pdf>

Please feel free to contact us, if you have any questions.

Best Regards

Edward Smith

Editorial Assistant

hrpub.editor@gmail.com

Horizon Research Publishing, USA

<http://www.hrpub.org>

Dear Indrawan Arifianto,
We have received the files. No worry.

On Thu, Jul 25, 2019 at 8:01 PM indrawan arifianto <indrawanarifianto1997@gmail.com> wrote:
Dear Edward Smith,

Well received with thanks. Can I still change the name of the author before it is published because there are some changes, and this is my last paper file that I have changed the name of the author and I also allow the file aggrament publication that I signed, thank you.

Best regards,

indrawan arifianto

On Mon, Jul 22, 2019 at 9:19 AM Edward Smith <hrpub.editor@gmail.com> wrote:

Dear Indrawan Arifianto, Muhammad Rangga Hadisiswoyo, Salim Burdah and Rahmat Alamtaha,

We're the partner of The 4th InternationalConference on Computing, Mathematics and Statistics 2019 (iCMS2019).

Your paper entitled **Modelling Temperature Effect on (Transverse Electric) TE mode Shape of optical Silica Waveguide** has been accepted for publication in Universal Journal of Electrical and Electronic Engineering, which is indexed by SCOPUS. Till now, 6 volumes 26 issues have been published.

For more detailed information, please refer to our website:
http://www.hrpub.org/journals/jour_info.php?id=49

Herewith attached are the Acceptance Letter and the Publication Agreement. Please complete the Publication Agreement and send a scanned version to us.

Look forward to hearing from you soon.

Please acknowledge receipt of this email.

Best Regards

Edward Smith
Editorial Assistant
hrpub.editor@gmail.com
Horizon Research Publishing, USA
<http://www.hrpub.org>
